IN THE CLAIMS

- 1 74. (canceled)
- 75. (new) An electronic device, comprising:
 - a plurality of integrated circuit packages;
- a contact surface electrically connected to each of said packages; and

an integrated circuit package support extending from said surface and in contact with each integrated circuit package, wherein the integrated circuit packages extend from the surface by a first distance and the support extends from the contact surface a second distance.

- 76. (new) The device of claim 75, wherein each of said packages is contacted on its upper end.
- (new) The device of claim 75, wherein said support includes a pair of surfaces which engage each of said packages on two opposed surfaces, sandwiching said packages.
- (new) The device of claim 77, wherein said support is resiliently biased against the sides of said packages.
- 79. (new) The device of claim 78, wherein said support contacts the side edges of said packages.
- 80. (new) The device of claim 75, wherein said support is made of a heat conducting material.
- (new) The device of claim 80, wherein said material is a conformal material.
 - 82. (new) The device of claim 80, wherein said material is

a foam having heat conductive particles dispersed through it to increase its heat conductivity.

- 83. (new) The device of claim 79, wherein said support includes outwardly extending tabs arranged to engage depressions in said packages.
- 84. (new) The device of claim 77, wherein said support is made at least in part of plastic foam.
- (new) The device of claim 84, wherein said support is 85. made of plastic foam with a plurality of slots formed therein, each slot sized to resiliently engage one of said modules.
- 86. (new) The device of claim 85, wherein said foam includes adhesive on its bottom to secure said foam to said surface.
- (new) The device of claim 75 wherein the extent to which the support contacts the integrated circuit package is a third distance that is either equal to less than the second distance and less than the first distance.